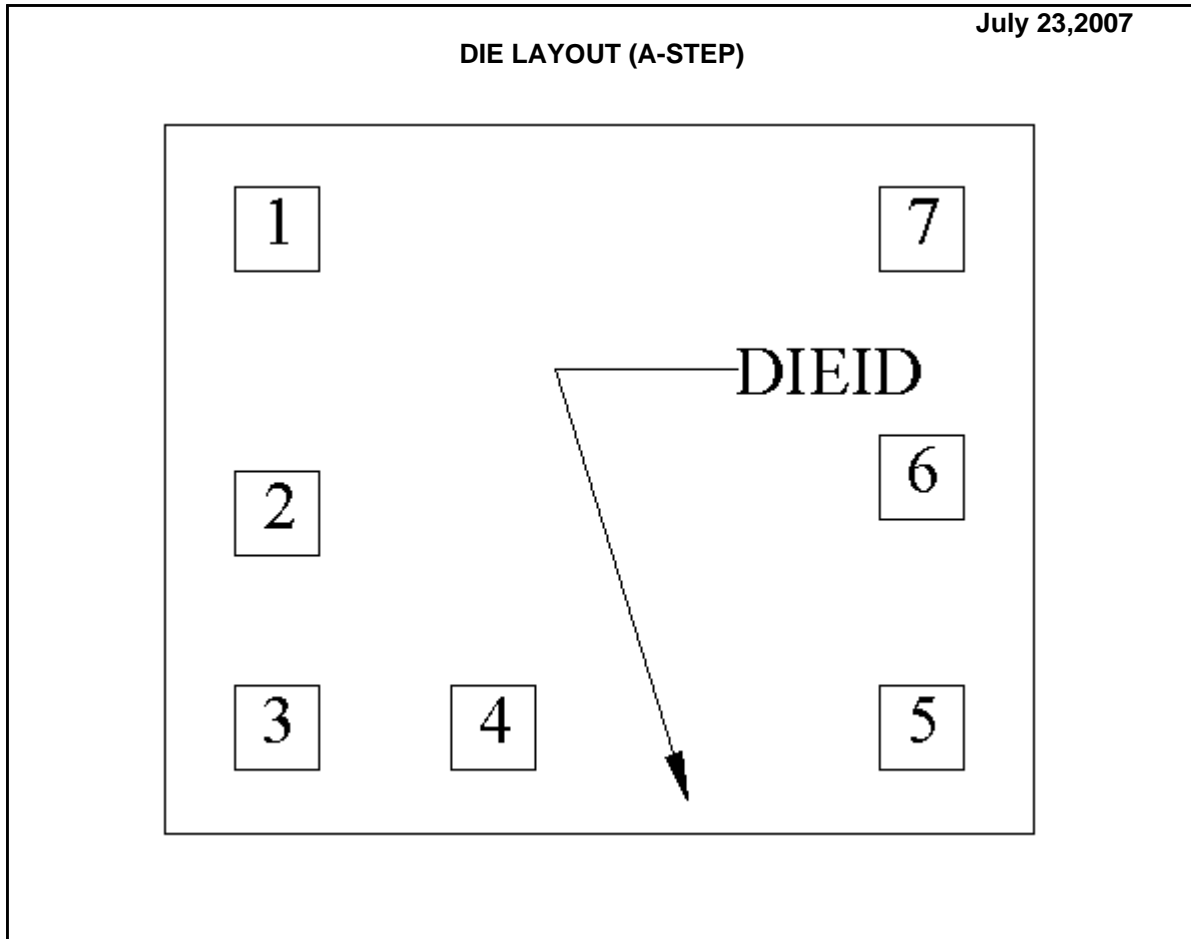


**LMH6639 MDC MWC
190MHZ RAIL-TO-RAIL OUTPUT AMPLIFIER WITH DISABLE**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6639A	Bond Pad Opening Size (min)	90µm x 90µm
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	927µm x 757µm 36.5mils x 29.8mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	229µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	Y
INPUT -	1	-345	267	90	x	90
NC	2	-345	-36	90	x	90
INPUT +	3	-345	-265	90	x	90
V -	4	-113	-265	90	x	90
OUTPUT	5	345	-265	90	x	90
V+	6	345	1	90	x	90
/SD	7	345	267	90	x	90

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